

**Amendments to the Claims**

Please replace all prior listings of the claims with the following.

Listing of the Claims

1. (Cancelled)
2. (Cancelled)
3. (Cancelled)
4. (Cancelled)
5. (Currently Amended) An apparatus for cleaning and shaping a probe tip comprising:
  - a support structure having a surface; and
  - a pad formed on said surface of said support structure, wherein said pad comprises a plurality of alternating layers of an adhesive layer and an abrasive layer, said plurality of alternating layers including at least two abrasive layers~~an adhesive and a plurality of abrasive particles in contact with said adhesive;~~
  - wherein each of said adhesive layer includes an adhesive ~~is located in an adhesive layer and wherein each of said abrasive layer includes a plurality of abrasive particles, is located in an abrasive layer;~~ and
  - ~~wherein said pad further comprises a plurality of alternating layers of said adhesive layer and said abrasive layer.~~
6. (Original) The apparatus of claim 5 wherein at least one of said abrasive layers comprises abrasive particles of a different size than the abrasive particles of another abrasive layer.
7. (Original) The apparatus of claim 6 wherein the size of the abrasive particles increases for each abrasive layer that is further from the support structure.

8. (Currently Amended) An apparatus for cleaning and shaping a probe tip comprising:  
a support structure having a surface;  
a pad formed on said surface of said support structure, wherein said pad  
comprises a plurality of composite layers, each of said composite layers including an  
adhesive and a plurality of abrasive particles in contact with said adhesive; ~~and~~  
~~—— a composite layer comprising said adhesive and said plurality of abrasive particles.~~

9. (Cancelled)

10. (Currently Amended) The apparatus of claim 9-8 wherein at least one of said  
composite layers comprises abrasive particles of a different size than the abrasive  
particles of another of said composite layers.

11. (Currently Amended) The apparatus of claim 10 wherein the size of said abrasive  
particles increases for each of said composite layers that is further from the support  
structure.

12. (Currently Amended) The apparatus of claim 9-8 wherein at least one of said  
composite layers comprises abrasive particles of a different material than the abrasive  
particles of another composite layer.

13. (Cancelled)

14. (Currently Amended) ~~An~~ The apparatus of claim 8 for cleaning and shaping a probe  
tip comprising:  
~~—— a support structure having a surface; and~~  
~~—— a pad formed on said surface of said support structure, wherein said pad~~  
~~comprises an adhesive and a plurality of abrasive particles in contact with said adhesive;~~

wherein the support structure is a semiconductor wafer, wherein the adhesive is an acrylic adhesive, and wherein the abrasive particles are diamond particles.

15. (Currently Amended) A method for cleaning and shaping a probe tip comprising the steps of: inserting the probe tip into a multi-layered adhesive and abrasive particle pad, said pad including a plurality of abrasive layers including abrasive particles, said abrasive layers being separated by an adhesive material; and extracting the probe tip.

16. (Original) The method of claim 15 wherein the step of inserting the probe tip comprises inserting the probe tip a predetermined distance into the pad, wherein said predetermined distance is a function of tip length and pad thickness.

17. (Original) The method of claim 15 wherein the steps of inserting and extracting are performed on-line.

18. (Currently Amended) The method of claim 15 wherein ~~in the inserting step said multi-layer adhesive and abrasive pad comprises abrasive layers, wherein~~ at least one of said abrasive layers has abrasive particles having a different size than the abrasive particles of at least one other abrasive layer.

19. (Currently Amended) The method of claim 15 wherein ~~in the inserting step, said multi-layer adhesive and abrasive pad comprises a plurality of composite layers, wherein~~ at least one of said abrasive layers is a composite layers including~~has an adhesive and~~ abrasive particles having a different size than the abrasive particles of at least one other ~~composite abrasive~~ layer.

20. (Cancelled)

21. (Previously presented) A method of making a probe tip cleaning and shaping pad comprising the steps of:

- applying an adhesive layer to a support structure;
  - applying a plurality of abrasive particles to said adhesive layer to form an abrasive particle layer; and
  - heating the support structure,
- wherein the step of applying said adhesive layer further comprises rolling the adhesive layer with a rolling tool to remove air bubbles; and
- wherein the step of applying the plurality of abrasive particles comprises brushing the plurality of abrasive particles on to said adhesive layer.

22. (Previously presented) A method of making a probe tip cleaning and shaping pad comprising the steps of:

- applying an adhesive layer to a support structure;
  - applying a plurality of abrasive particles to said adhesive layer to form an abrasive particle layer; and
  - heating the support structure,
- wherein the step of applying an adhesive layer further comprises placing the adhesive layer on the support structure and rolling over the adhesive layer with a rolling tool to remove air bubbles; and
- wherein the step of applying the plurality of abrasive particles comprises brushing the plurality of abrasive particles on to said adhesive layer.

23. (Original) The method of claim 21 wherein in the step of applying the plurality of abrasive particles, said plurality of abrasive particles comprises varying grit sizes for different layers; and wherein said abrasive particles comprise diamond particles.

24. (Original) The method of claim 23 wherein the step of applying the plurality of abrasive particles further comprises graduating the size of the abrasive particles from

smallest to largest with increasing distance of layers from the support structure.

25. (Original) The method of claim 24 wherein the step of applying the adhesive layer further comprises using an adhesive backing layer that can be peeled off, leaving the adhesive behind.